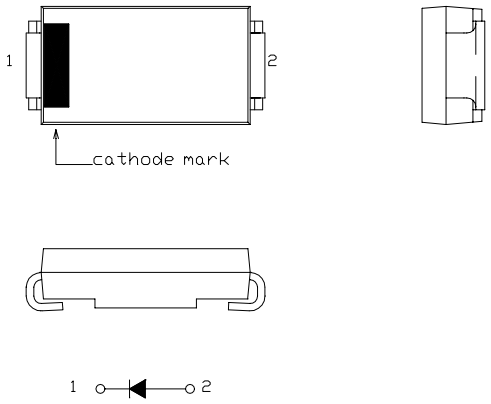
Nihon Inter Electronics Corporation

FRD Type : NSF03A60

OUTLINE DRAWING



FEATURES

* **FLAT-PAK** Surface Mount Device
* Ultra Fsat Recovery
* High Surge Capability
* Low Forward Voltage Drop
* Low Power Loss, High Efficiency
* Packaged in 16mm Tape and Reel
* Not Rolling During Assembly

Maximum Ratings

Approx Net Weight:016g

Rating	Symbol	NSF03A60			Unit
Repetitive Peak Reverse Voltage	V_{RRM}	600			V
Average Rectified Output Current	I_O	1.1	Ta=27 ℃ *1	50Hz Half Sine Wave Resistive Load	A
		3.0	T1=79 ℃ *2		
RMS Forward Current	$I_{F(RMS)}$	4.71			A
Surge Forward Current	I_{FSM}	45	50Hz Half Sine Wave,1cycle Non-repetitive		A
Operating JunctionTemperature Range	T_{jw}	-40 to +150			℃
Storage Temperature Range	T_{stg}	-40 to +150			℃

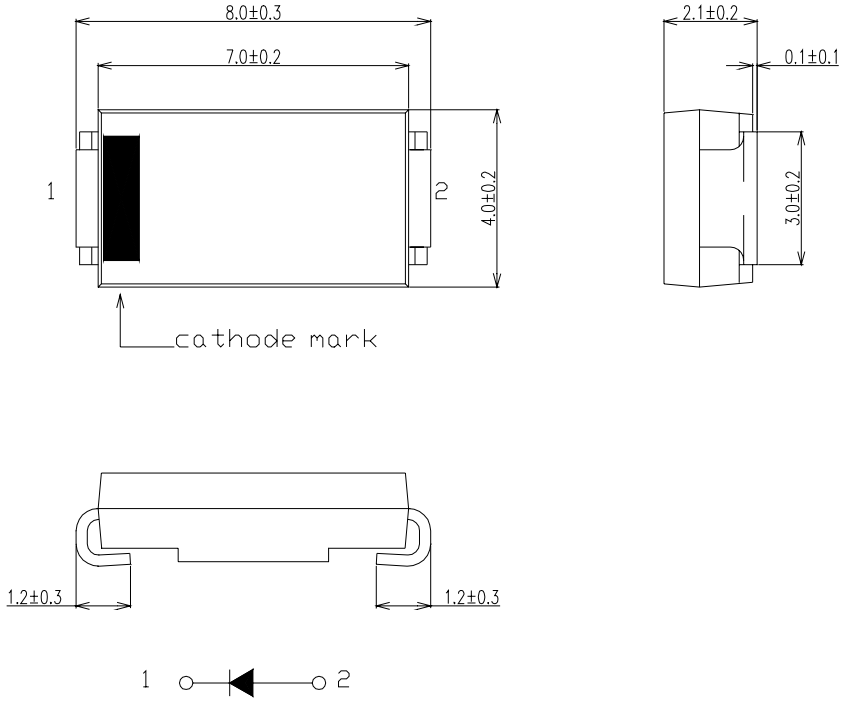
Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current	I_{RM}	Tj= 25℃, V_{RM}= V_{RRM}	-	-	20	μA
Peak Forward Voltage	V_{FM}	Tj= 25℃, I_{FM}= 3.0A	-	-	1.7	V
Reverse Recovery Time	trr	Ta= 25℃, I_{FM}=3 A –di/dt=50A/μs			35	ns
Thermal Resistance	$Rth_{(j-a)}$	Junction to Ambient *1	-	-	89	℃/W
	$Rth_{(j-l)}$	Junction to Lead	-	-	13	

*1 Alumina Substrate Mounted (Soldering Lands=2x3.5mm,Both Sides)

*2 Tl= Lead Temperature

NSF03A60 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD